

Exhibit A

Invention Disclosure

Confidential (When Completed)

Full Name(s) of Inventor(s)		Employee No.	Department	Dept. Code	Tel No.	For Use by IP Law Disclosure No.
English	Chinese					
HMChen	陳惠生	058	IEPM			M6G02-005
CKChou						Received Date (Time Stamp)
JYLee	劉盈智	006				
HTLiu						

Title of Invention -

- English: A Clean process for finishing IC product
- Chinese

Background Information - Current Practice and Disadvantages

All the final process steps of metal pad or metal bump are chemical process in the current IC process.

There is micro-contamination absorbed on the final metal surface.

Over killed problem happen sometimes during chip probing due to micro-contamination on metal pad.

Main Points of Claim (Please List Item by Item)

Add in a physical clean after finish IC process before chip probing.

The physical clean can be a inner gas plasma, sputtering etch, ion mill or any bombardment clean.

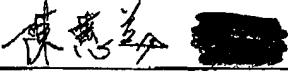
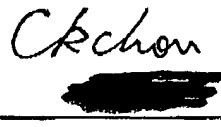
Problem Solved or Improvements Obtained by this Invention (Please List Item by Item)

To reduce over killed problem during chip probing.

Keyword Search for Patent/Literatures

Patent/Literatures Search Result (Please Specify Similar Patent No. and Literature Citation)

Detailed Description of Invention - (Continued Next Page)

Witnesses: The Two Witnesses whose Signatures appear below have <u>Read and Understand</u> this Entire Invention Disclosure.		Disclosure Submitted by	
Signature of Witness	Date	Inventor's Signature Date	Inventor's Signature Date
Eric L			
		Inventor's Signature Date	Inventor's Signature Date
Signature of Witness	Date		
陳盈智			

Invention Disclosure

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Detailed Description of Invention – Continued

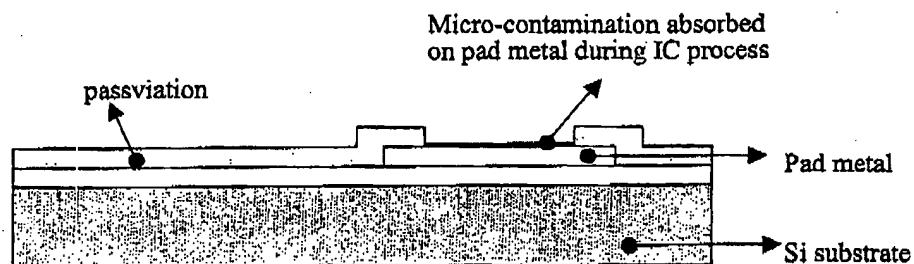
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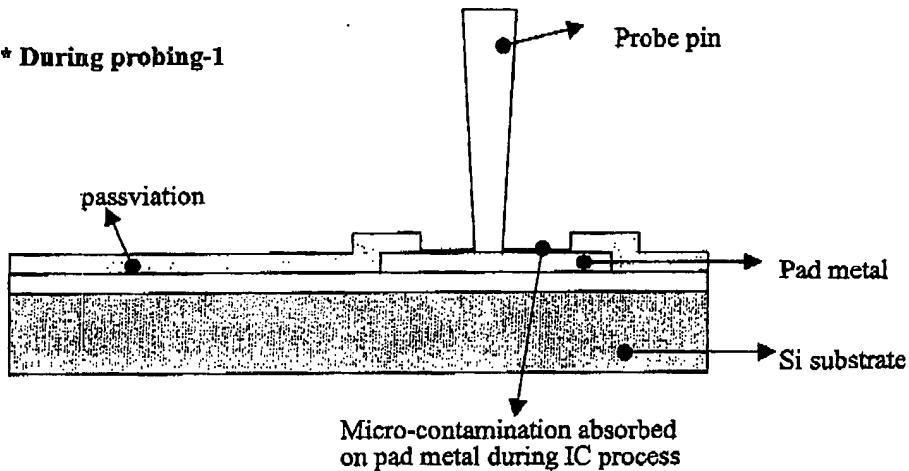
MES 02-005

Current practice 1:

* After finish IC process



* During probing-1



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Inventor's Signature Date

Signature of Witness Date

Inventor's Signature Date

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Signature of Witness Date



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Detailed Description of Invention – Continued

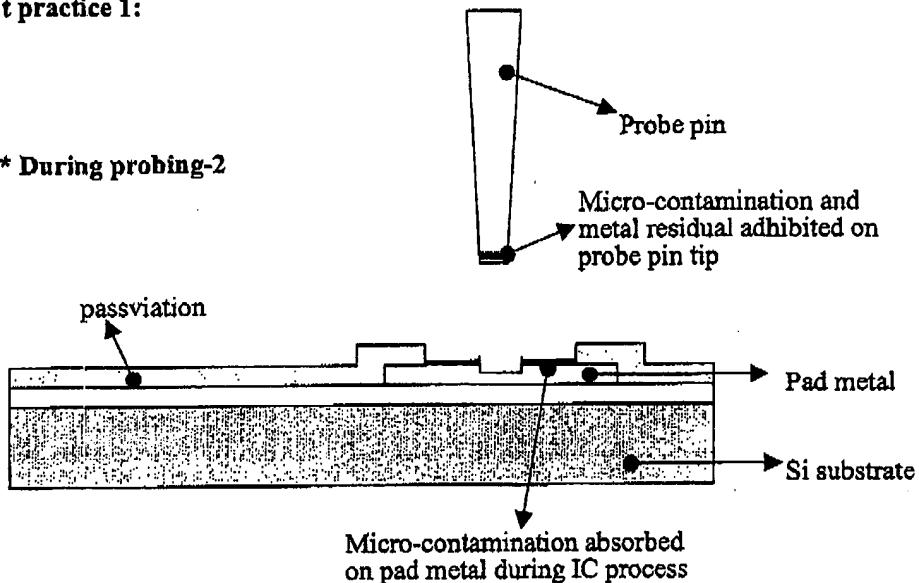
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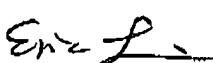
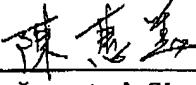
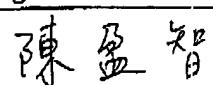
Disclosure No.

1A6902-005

Current practice 1:

* During probing-2



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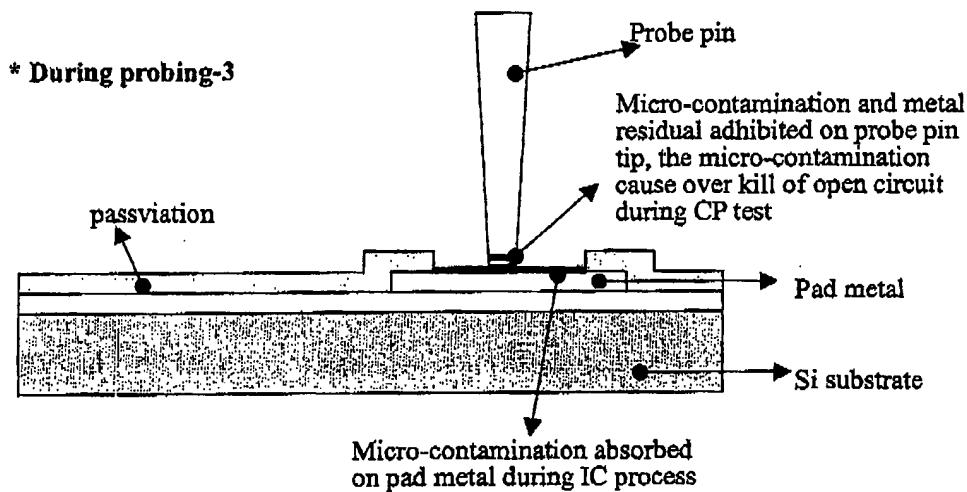
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Disclosure No.

MEG02-005

Current practice 1:



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Signature of Witness Date

Eric Li

Disclosure Submitted by

Inventor's Signature Date

陳惠生

Inventor's Signature Date

Ckchan

Signature of Witness Date

陳盈君

Inventor's Signature Date

JT Lee

Inventor's Signature Date

HT Lin



Invention Disclosure

Confidential (When Completed)

Detailed Description of Invention – Continued

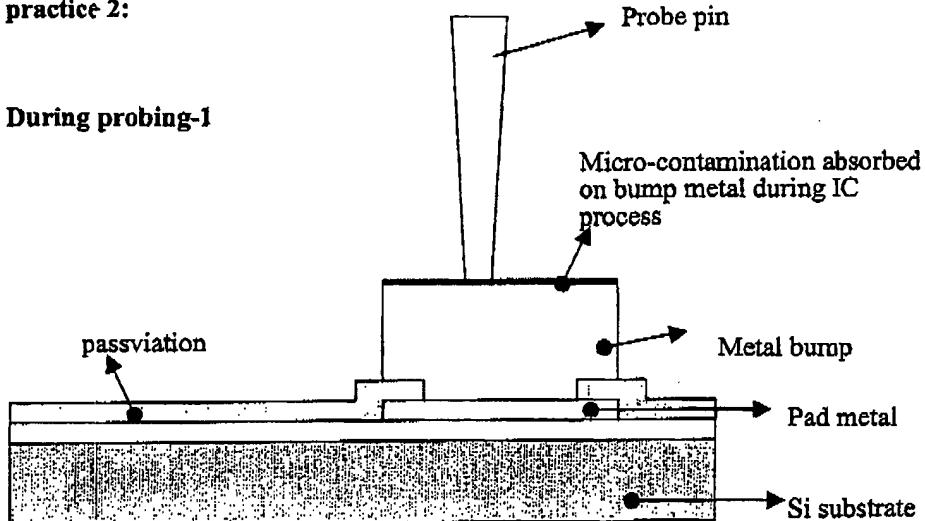
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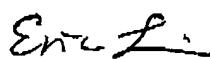
Current practice 2:

* During probing-1

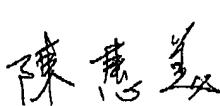
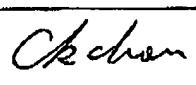


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Signature of Witness Date



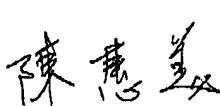
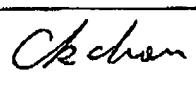
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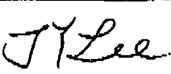
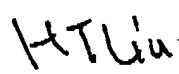
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Inventor's Signature Date

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Inventor's Signature Date



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Detailed Description of Invention – Continued

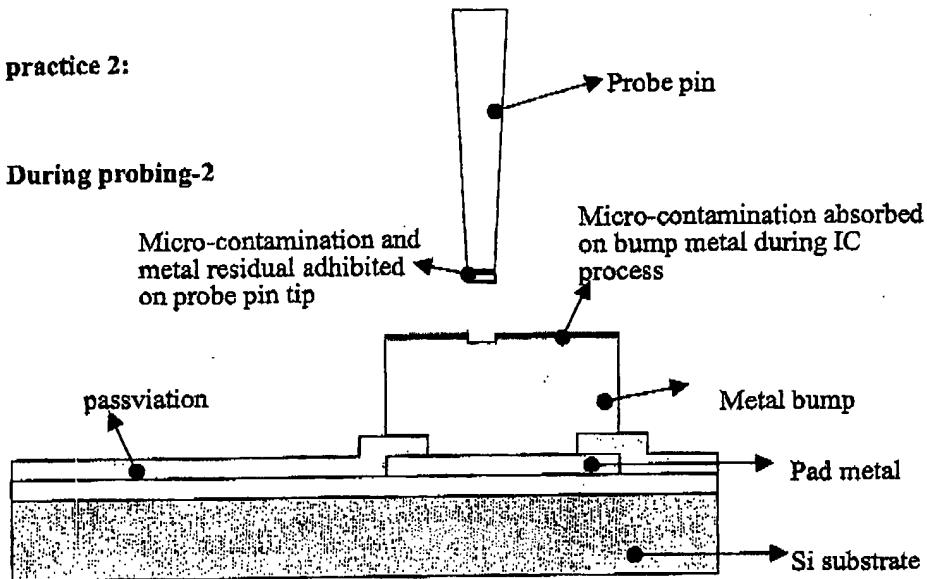
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Disclosure No.

MEG02-005

Current practice 2:

* During probing-2



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Signature of Witness Date

Eric Lee

Signature of Witness Date

陳盈智

Disclosure Submitted by

Inventor's Signature Date

陳盈智

Inventor's Signature Date

Okchan

Inventor's Signature Date

JY Lee

Inventor's Signature Date

HT Lin

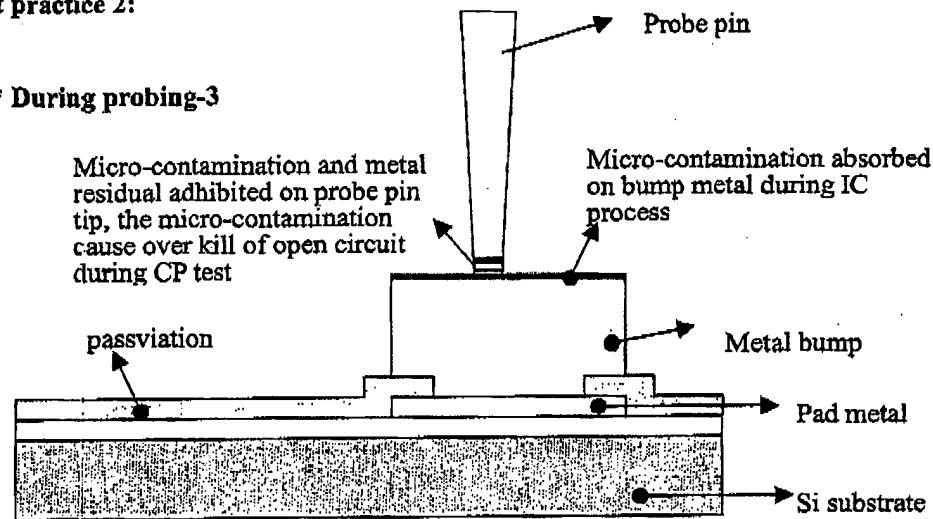
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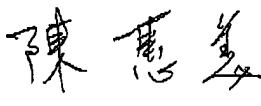
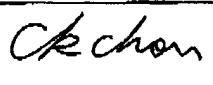
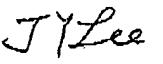
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Current practice 2:

* During probing-3



Witnesses: The Two Witnesses whose Signatures appear below have <u>Read</u> and <u>Understand</u> this Entire Invention Disclosure.		Disclosure Submitted by	
Signature of Witness	Date	Inventor's Signature Date	Inventor's Signature Date
Eric L.			
		Inventor's Signature Date	Inventor's Signature Date
陳盈智			



Invention Disclosure

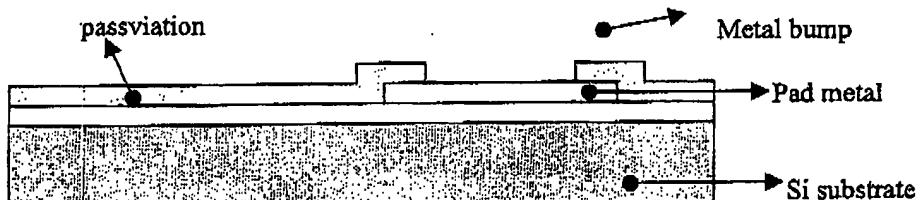
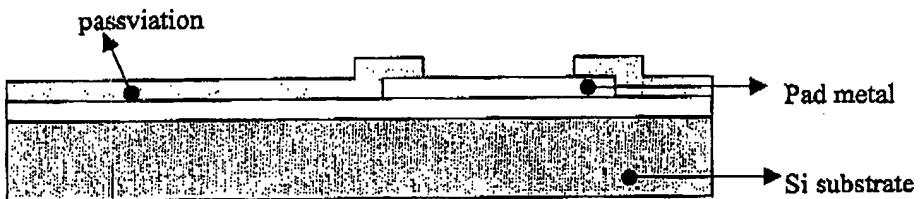
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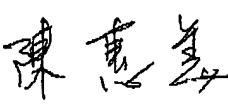
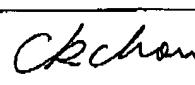
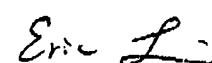
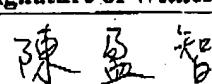
Detailed Description of Invention – Continued	For Use by IP Law Disclosure No. MEG02-005
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New invention:

* After finish IC process

Add in a physical clean ex. Ar sputtering or ion mill to remove micro-contamination. The surface become very clean with no chemical absorption.



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	Inventor's Signature Date	Inventor's Signature Date
		
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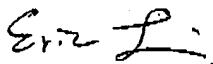
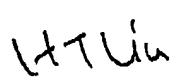
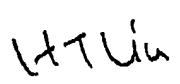
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Detailed Description of Invention – Continued	For Use by IP Law Disclosure No. MEG 02-005
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New invention:

The over kill problem will be eliminated during chip probing after this physical surface clean

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Full Name(s) of Inventor(s)		Employee No.	Department	Dept Code	Tel No.	For Use by IP Law
English	Chinese				310 13	Disclosure No.
						ME602-005
						Received Date
					GEORGE D. SAUER & ASSOCIATES POUGHKEEPSIE, NY, U.S.A. (Name Stamp)	

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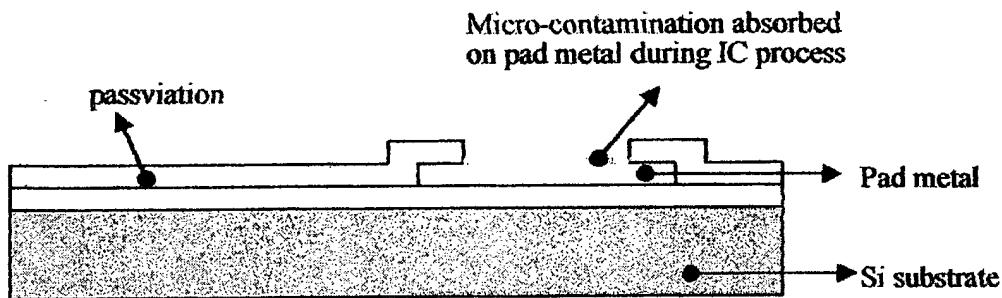
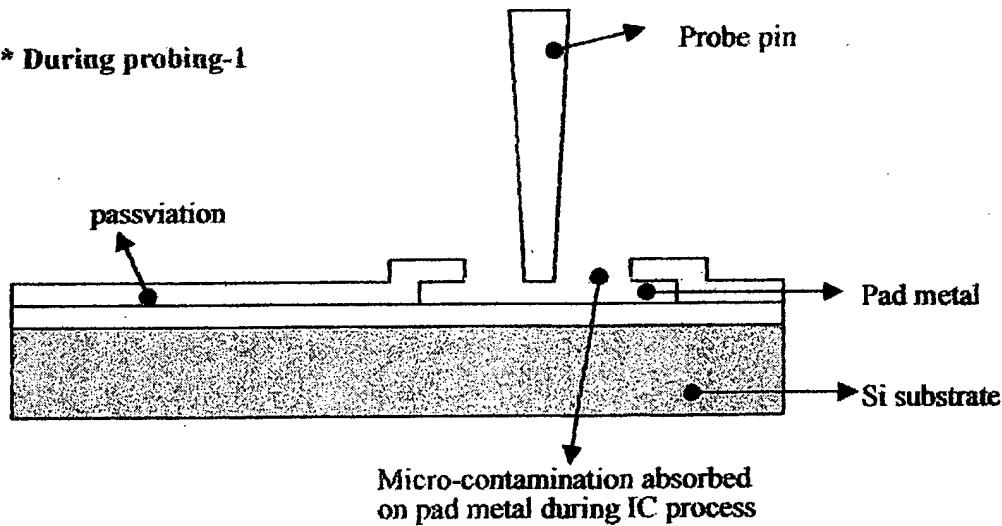
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Current practice 1:*** After finish IC process***** During probing-1**

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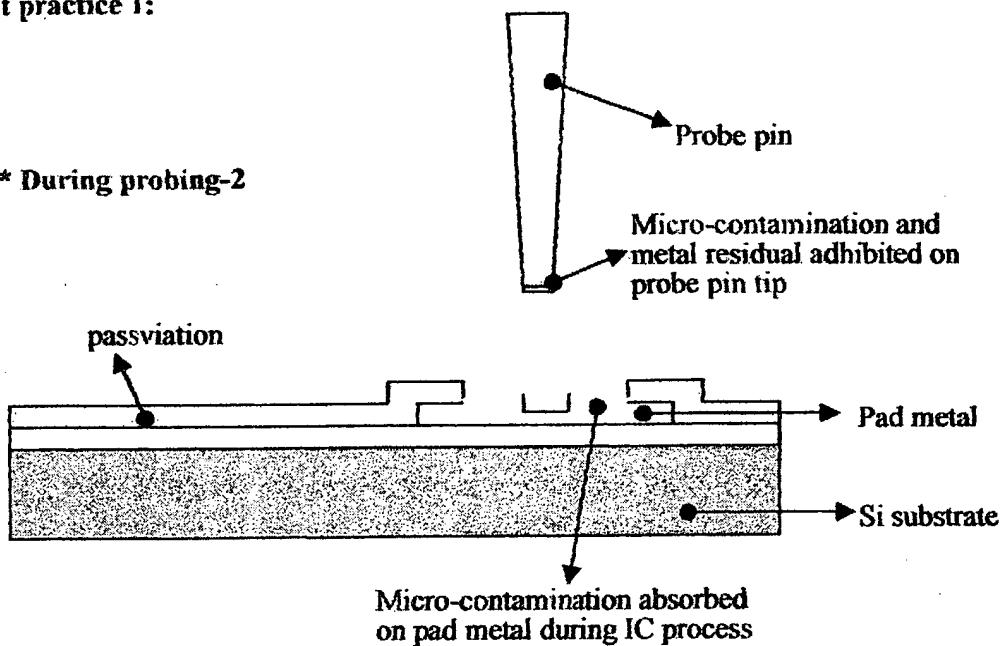
Inventor's Signature Date

Inventor's Signature Date

Signature of Witness Date

Inventor's Signature Date

Inventor's Signature Date

Current practice 1:*** During probing-2**

Witnesses: The Two Witnesses
whose Signatures appear below
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Disclosure Submitted by

Signature of Witness Date

Inventor's Signature Date

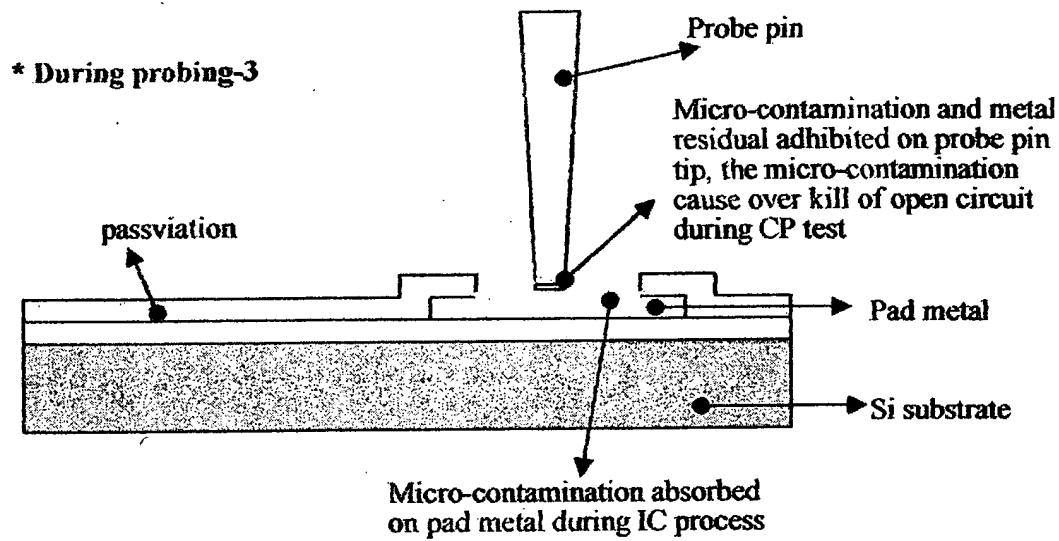
Inventor's Signature Date

Signature of Witness Date

Inventor's Signature Date

Inventor's Signature Date

Current practice 1:



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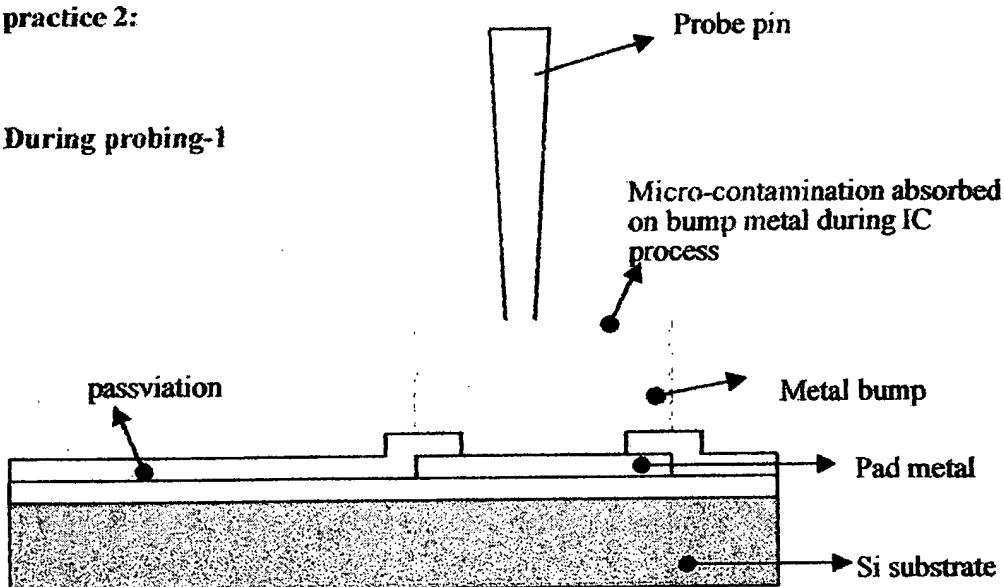
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Inventor's Signature Date

Inventor's Signature Date

Inventor's Signature Date

Current practice 2:*** During probing-1**

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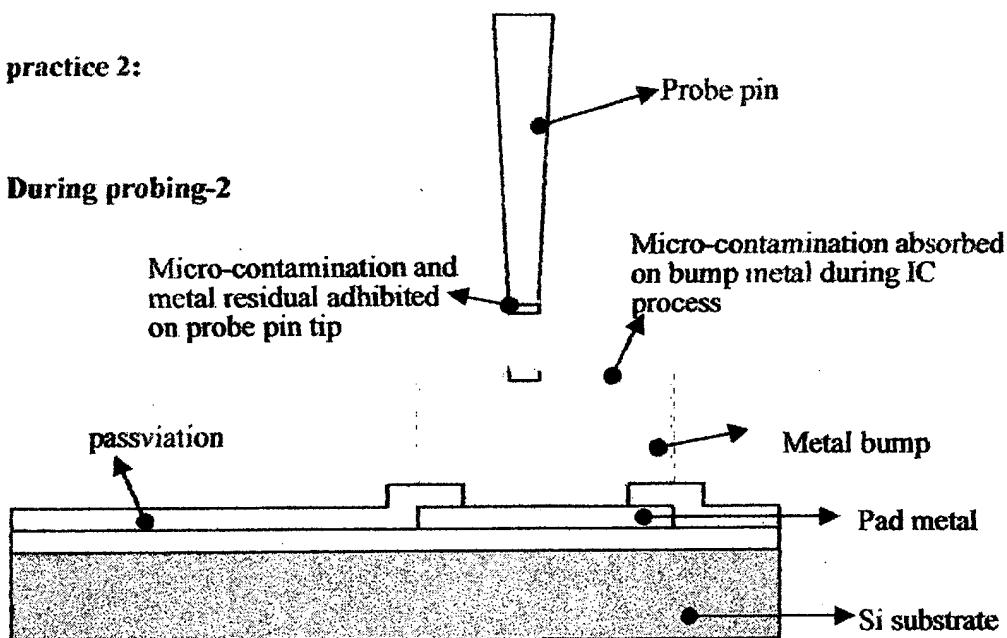
Inventor's Signature Date

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Current practice 2:*** During probing-2**

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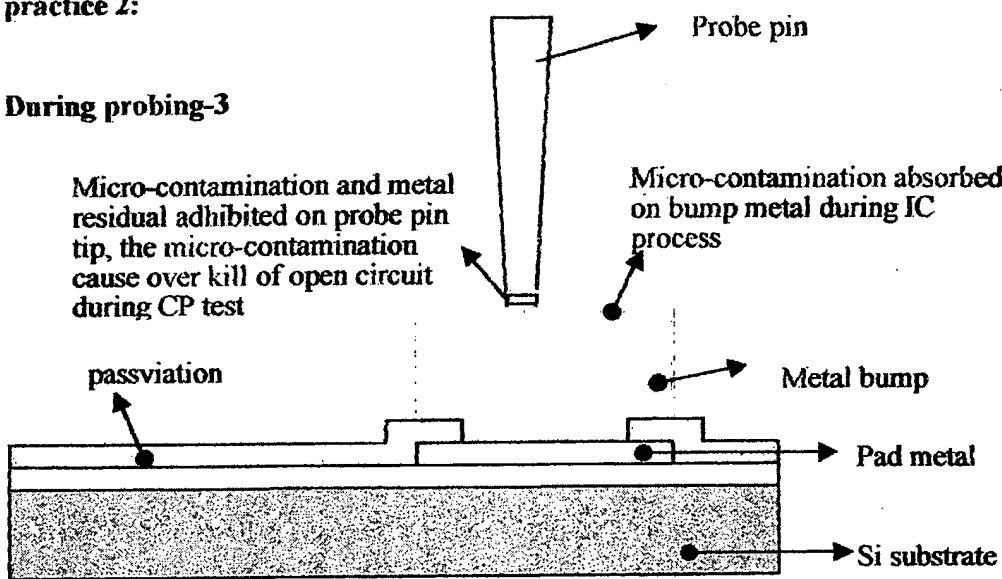
Inventor's Signature Date

Signature of Witness Date

Current practice 2:

*** During probing-3**

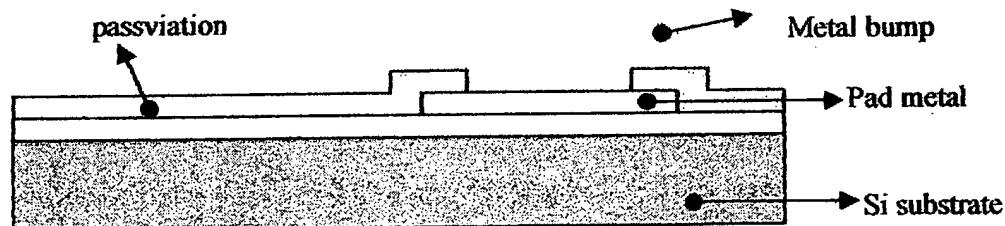
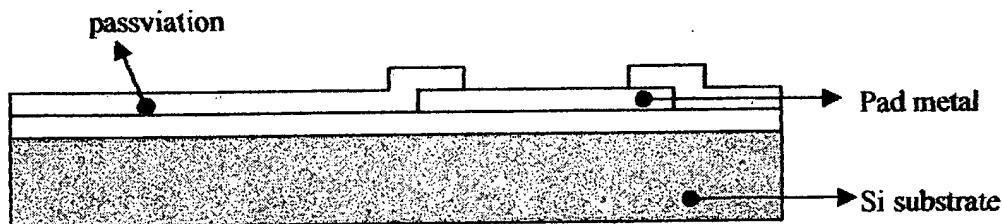
Micro-contamination and metal residual exhibited on probe pin tip, the micro-contamination cause over kill of open circuit during CP test



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New invention:

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